# RP201208-ATC3

# SMD Type Red Emitter

#### Features

- Top view 0805 package
- Viewing Angle =  $\pm 70^{\circ}$
- Compatible with infrared and vapor phase reflow solder process
- High reliability
- Ultra bright Red
- RoHS compliance

### Applications

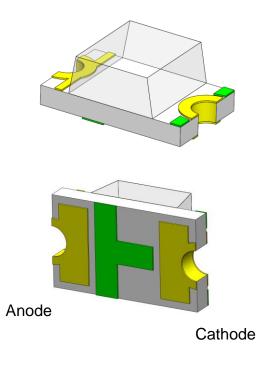
- Optical indicator.
- Switch and Symbol Display.

### Description

The RP201208-ATC3 is an AlGaInP Red LED housed in a miniature SMD package. The device has a dominant wavelength of 625 nm LED.

### **Package Outline**

### Schematic



Cathode (-) node



### Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
lF	Continuous Forward Current	25	mA	
IFP	Peak Forward Current	60	mA	1
V <sub>R</sub>	Reverse Voltage	5	V	
T <sub>opr</sub>	Operating Temperature	-40 ~ +85	0C	
T <sub>stg</sub>	Storage Temperature	-40 ~ +100	0C	
T <sub>sol</sub>	Soldering Temperature	260	0C	2
PD	Power Dissipation at(or below) 25°C Free Air Temperature	65	mW	

#### Electro-Optical Characteristics TA = 25°C (unless otherwise specified)

#### **Optical Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
lv	Luminous Intensity	I <sub>F</sub> =20mA	62	-	200	mcd	3
λd	Dominant Wavelength	I <sub>F</sub> =20mA	615	-	630	nm	4
θ1/2	Angle of Half Intensity	I <sub>F</sub> =20mA	-	±70	-	deg	

#### **Electrical Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward Voltage	I <sub>F</sub> =20mA	1.7	-	2.5	V	5
IR	Reverse Current	V <sub>R</sub> =5V	-	-	1	μA	

Notes:

- 1. IFP Conditions--Pulse Width  $\leq~100 \mu s$  and Duty  $\leq~10\%.$
- 2. Soldering time  $\leq 10$  seconds.
- 3. Bin Range of Luminous Intensity

Bin Code	Min	Max	Unit	Condition
m	62	89		
n	89	130	mcd	I⊧=20mA
о	130	200		

Tolerance of: Luminous Intensity ±10%



#### 4. Bin Range of Dominant Wavelength

Bin Code	Min	Max	Unit	Condition
J1	615	620		
J2	620	625	nm	I⊧=20mA
J3	625	630		

Tolerance of Dominant Wavelength: ±1nm.

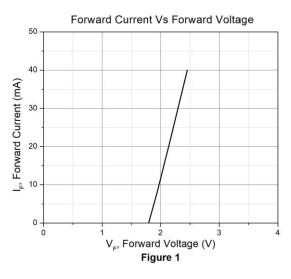
#### 5. Bin Range of Forward Voltage

Bin Code	Min	Max	Unit	Condition
V4	1.7	1.9		
V5	1.9	2.1	V	
V6	2.1	2.3	V	l⊧=20mA
V7	2.3	2.5		

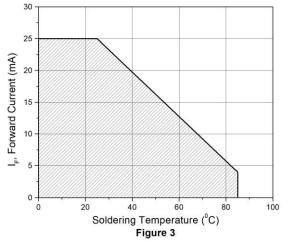
Tolerance of Forward Voltage  $\pm 0.1$ V.



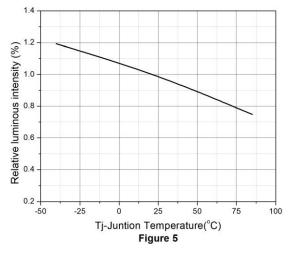
### **Typical Characteristic Curves**



Forward Current Vs Soldering Temperature



Relative Luminous Intensity Vs Juntion Temperature



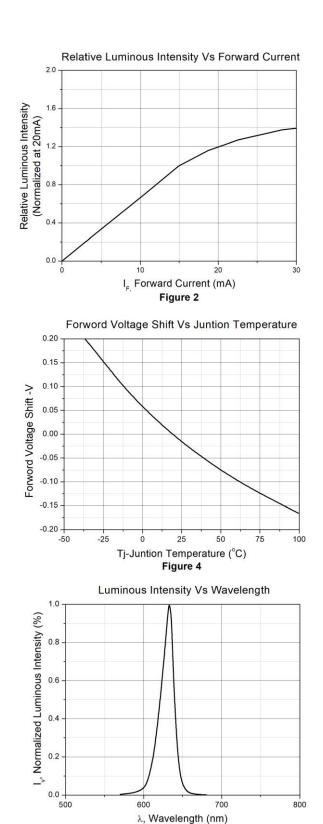
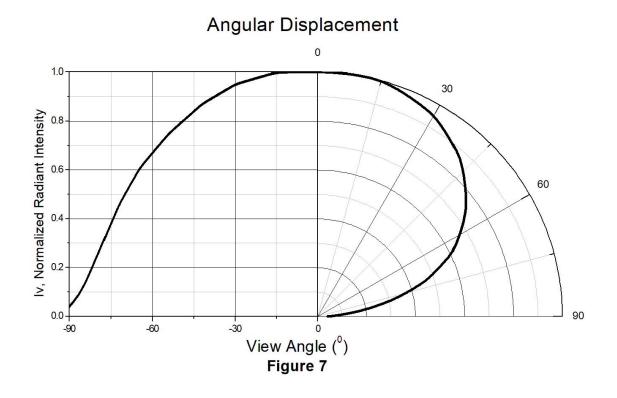


Figure 6

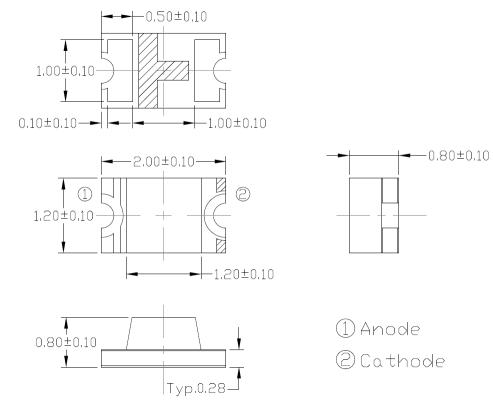
CT Micro Proprietary & Confidential



## **Typical Characteristic Curves**



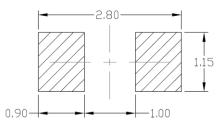




#### Package Dimension All dimensions are in mm, unless otherwise stated

Note: Tolerance unless mentioned is  $\pm 0.1$ mm.

#### Recommended Soldering Mask All dimensions are in mm, unless otherwise stated



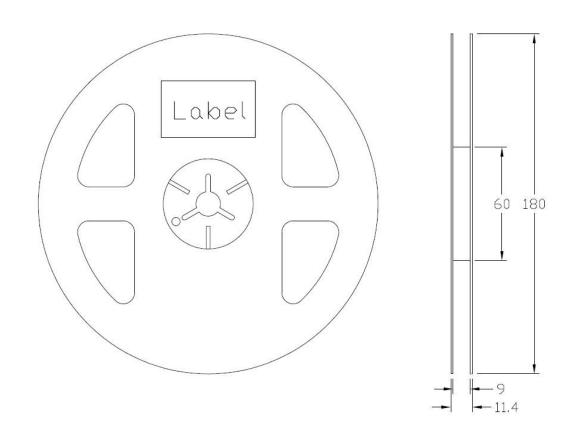
Note: Tolerance unless mentioned is ±0.1mm.

### **Ordering Information**

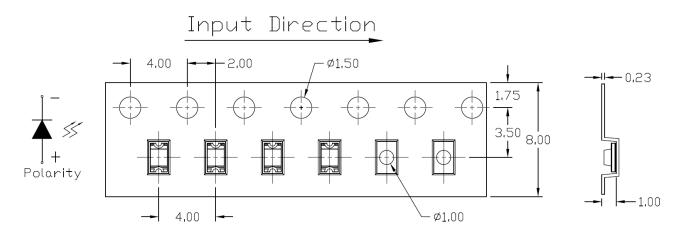
Part Number	Description	Quantity
RP201208-ATC3	Tape & Reel	3000 pcs



#### Reel Dimension All dimensions are in mm, unless otherwise stated



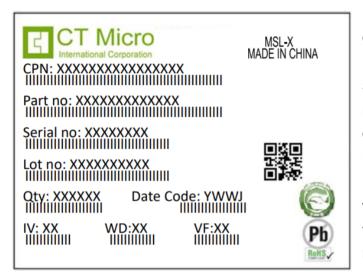
#### Tape Dimension All dimensions are in mm, unless otherwise stated



Note: Tolerance unless mentioned is ±0.1mm.



### Label Form Specification



CPN : Customer Part Number Part no: CTM Production Number Serial no: Production Number Lot no: Lot number Q'ty: Packing Quantity Date Code: Manufacture Date IV : Bin Code of Luminous Intensity WD : Bin Code of Dominant Wavelength VF : Bin Code of Forward Voltage MADE IN CHINA: Production Place

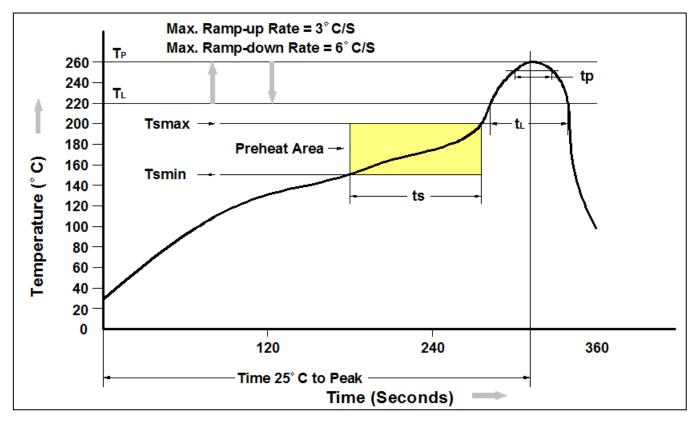
### **Storage Condition**

- 1. Do not open moisture proof bag before the products are ready to use.
- 2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening. Shelf life of non-opened bag is 12 months after the bag sealing date.
- 3. After opening the moisture barrier bag floor life is 1 year at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
- 4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



# RP201208-ATC3 SMD Type Red Emitter

### **Reflow Profile**



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate $(T_P \text{ to } T_L)$	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



### DISCLAIMER

CT MICRO RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. CT MICRO DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

CT MICRO ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT EXPRESS WRITTEN APPROVAL OF CT MICRO INTERNATIONAL CORPORATION.

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instruction for use provided in the labelling, can be reasonably expected to result in significant injury to the user.
- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.